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 TI **Copper** alloys for leads in semiconductor devices
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 PA Tamagawa Metal and Machinery Co., Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 4 pp.
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PI	JP 62093325	A2	19870428	JP 1985-232559	19851018
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AB	<p>The Cu alloys contain Fe 2-2.4, P 0.001-0.1, Zn 0.01-1, and Mg 0.001-0.1%. The Mg addn. improves heat resistance and strength without lowering elongation and elec. cond. The Cu alloys show good solderability. Thus, molten Cu alloy (contg. Fe 2.02, P 0.00188, Zn 0.012, and Mg 0.002%) was semicontinuously cast into an ingot slab 150 mm thick, and hot-rolled into a plate 11 mm thick. The trimmed plate was alternately cold rolled and annealed to manuf. a strip 0.25 mm thick, and then annealed for strain relief at 250-350.degree.. The strip showed tensile strength 52.1 kg/mm², elongation 5%, elec. cond. 64% of IACS, and softening point 410.degree.. A solder coating showed good adhesion when the strip was bent after heating in air at 150.degree. for 500 h.</p>				